

Doc. Number:	102-0014-000	Revision:	Α	Total Pages:	5			
Doc. Title:	<b>3U Industrial Computer – Product End-of-Life Disassembly Instructions</b>							

## Printed copies are for reference only. Please refer to the Premio Agile system for the controlled and latest copy.

## Note: Tools required for disassembly

- Phillips screwdriver
- Wire cutters
- Needle-Nose Pliers

Product Category: 3U Industrial Computer Marketing Name: BPI-XX-PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of Premio products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## **1.0 Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the table, as applicable.

Component or Material	Remarks	Qty	Location	Tools Needed for Disassembly	Disassembly Instructions
Battery (internal (1)) containing Mercury (Hg) / NiCad / Lithium / Other	Battery (Lithium) attached	1	Motherboard	None	<ol> <li>Remove the top cover of the chassis by removing the screws holding the cover using a phillips screwdriver.</li> <li>Locate the battery and battery holder</li> </ol>

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Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	None	0	N/A	N/A	3. N/A	on the MB. Push against battery release tab and pop out the lithium battery
Internal Fans	None	3	CPU, chassis (rear)	Phillips Screwdriver Needle-Nose Pliers Wire cutters	1.         2.         3.         4.         1.         2.         3.         4.         5.	First open the chassis by removing the screws holding the top cover. On the MB, locate the CPU fan Using the needle- nose pliers, gently squeeze the clips holding the fan to the heatsink Remove the fan <b>Chassis fans-</b> First open the chassis by removing the screws holding the top cover Locate the fans on the rear of the chassis Using the phillips screw the 4 screws holding the fans in place

	None	0	N/A	N/A	N/A
Mercury (Hg) in other applications					
Gas Discharge Iamps	None	0	N/A	N/A	N/A
Plastic containing brominated flame retardants other than in Printed Circuit Assemblies (3)	None	0	N/A	N/A	N/A
Liquid Crystal Displays with a surface greater than 100 cm <sub>2</sub>	None	0	N/A	N/A	N/A
PCBs with surface area >10 cm <sup>2</sup>	None	6	Motherboard /system board, HDD, VGA, NI cards (2), power supply module	Phillips Screwdriver, Wire cutters	<ol> <li>First remove the top cover of the chassis using a phillips screwdriver</li> <li>For PCB MB assemble, remove all connectors from the cabling going to the MB</li> <li>Remove the 8 screws holding the MB assembly into the chassis</li> <li>Lift out the MB PCB</li> <li>Remove all PCB modules by using the phillips screwdriver to remove the connector screw, then gently pull the boards out of the sockets.</li> </ol>

					<ol> <li>Remove the power supply module by first removing the 4 holding screws, then with the wire cutter, cut any wires from the power supply module</li> <li>Remove the power supply module</li> <li>For the HDD, Remove the 4 screws holding the HDD in place, remove the SATA cable connector</li> <li>Remove the HDD from the chassis</li> </ol>
Capacitor With PCB's	None	0	N/A	N/A	N/A
Capacitors with substances of concern (4) +height .25mm, diameter . 25mm or proportionately similar volume	None	0	N/A	N/A	N/A
Asbestos	None	0	N/A	N/A	N/A
Refractory ceramic fibers	None	0	N/A	N/A	N/A
Radio-active substances	None	0	N/A	N/A	N/A
Beryllium oxide and other forms of Beryllium	Ceramics, metal alloy, copper- beryllium alloy, catalyst, precipitation hardening alloy, Cu-Be alloy for	0	N/A	N/A	N/A

	spring, solder				
Gases – which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC)	None	0	N/A	N/A	N/A
Components with pressurized gas which need special attention (Pressure >1.5 bar)	None	0	N/A	N/A	N/A
Liquids if volume >10cl (or equivalence in weight, eg for PCB, oil)	None	0	N/A	N/A	N/A
Mechanical components that store mechanical energy (ie, springs) or equivalent parts which need special attention	None	0	N/A	N/A	N/A

1 Internal means that batteries can only be removed by opening the product by means of (a) tool(s)

- 2 Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95/EC and 2011/65/EC (RoHS Directive) or if their use is permitted through exemptions in the Annex Directive 2011/65/EC
- 3 To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2012/19/EC Annex VII requirement is understood to focus on plastic parts that weigh more than 25g
- 4 Substance of concern other than PCB, to be specified / addressed further in the context of Directive 2012/19/EC Annex VII national requirements and European developments

Please Note: Dispose of all items in accordance with regulatory requirements.

## **END OF DOCUMENT**